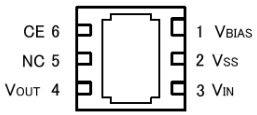
■PIN CONFIGURATIOIN

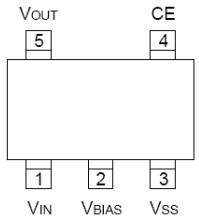
●USP-6C



USP−6C
(BOTTOM VIEW)

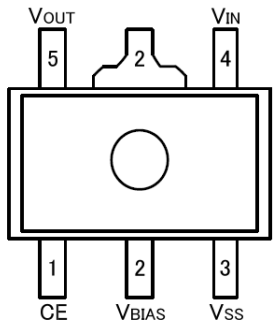
*The heat dissipation pad of the USP-6C package is recommended to solder as the recommended mount pattern and metal mask pattern for mounting strength. The mount pattern should be electrically opened or connected to the VBIAS (No.1) pin.

●SOT-25



SOT-25
(TOP VIEW)

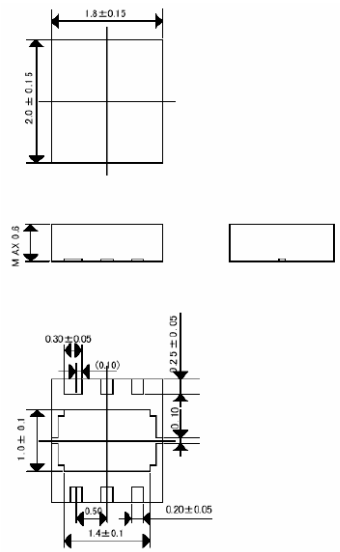
●SOT-89-5



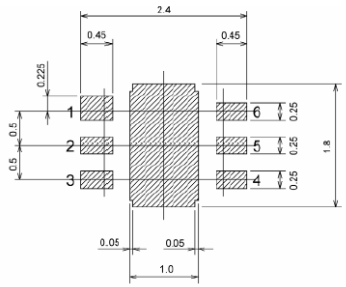
SOT−89−5
(TOP VIEW)

■PACKAGING INFORMATION

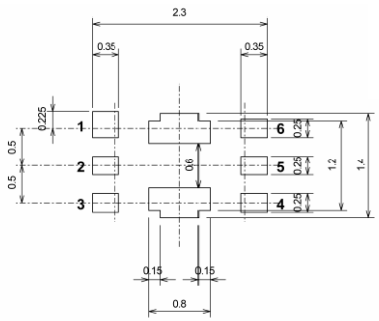
●USP-6C



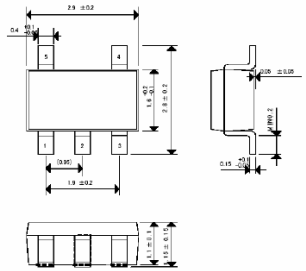
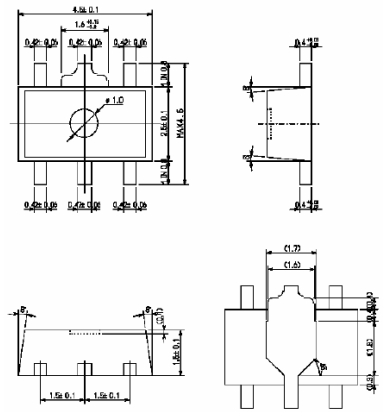
USP-6C Recommended Pattern Layout



USP-6C Recommended Metal Mask Design



●SOT-25



●SOT-89-5